Supplies Provided by NUFAB

Gowning
All required gowning supplies

Personal Protective Equipment (PPE)
All required PPE

Chemicals
Photoresists: SPR220.7, SU8-3050, SU8 3025, SU8 2002, SU8-3010, S1813, S1805, LOR 1A, LOR 5A, AZ 5214E-IR, AZ P4620, Polyimide PI2545, AZ nLOF2035
Developers: MF319, AZ 400K (1:4 and concentrated), SU8 Developer, AZ 917MIF, AZ 300MIF
Ebeam Resists: PMMA 950 A2, PMMA 950 A5, ZEP520A
Ebeam Developers: MIBK, ZED-N60, DisChargeH2Ox2 (anti-charging agent)
Resist Removers: Remover 1165, Nanostrip
Adhesion Promoters: HMDS, MCC Primer 80/20 (20% HMDS and 80% PM Acetate), SurPass 4000
Solvents: Acetone, 2-Propanol
Etchants: Chrome Etchant, Buffered Oxide Etch 6:1 and 10:1, Aluminum Etchant, Nanostrip, HF, Fe2O3 Etchant, Copper Etchant, Gold Etchant TFA, KOH, TMAH 25%, HBr, HCl, Citric acid, H2SO4, HNO3, H3PO4,

General Cleanroom Supplies
Silicon Wafers (various sizes)
Wafer and Mask Holders (various sizes)
Cleanroom Notebooks
Cleanroom Paper
Cleanroom Wipes (two types)
Storage Boxes
Petri Dishes
Aluminum Foil

Equipment Specific Supplies
AJA Sputter Targets: Cu, Al, Cr, Mo, Ti, Ni, Fe, W, Si, SiO2, Si3N4, ZnO, ITO, PZT, Ag, Au, Pt
AJA E-beam Evaporator: Crucibles for all materials
ALD Precursors: Triethylaluminum, Diethylzinc, Trimethyl(methylcyclopentadienyl)platinum(IV), 3-aminopropyltriethoxysilane, Tris(dimethylamino)siiane, Tetraakis(dimethylamido)hafnium(IV), Tetrakis(dimethylamido)titanium, Tetrakis(dimethylamido)zirconium(IV),
Tris(diethylamido)(tert-butylimido)tantalum(V), Molybdenum hexacarbonyl, Tetrakis(2,2,6,6-tetramethyl-3,5-heptanedionato)cerium(IV), Tetrakis(dimethylamino)tin(IV), Water, Ozone, Oxygen, Oxygen plasma, Hydrogen, Hydrogen plasma, Ammonia, and Ammonia plasma

**ALD Cook:** Trimethylaluminum, Tetrakis(dimethylamido) titanium, Tetrakis(dimethylamido) hafnium, Tetrakis(dimethylamido) zirconium

**Denton Thermal Evaporator:** Boats for all materials, chrome-coated tungsten rods

**Evaporation Materials:** Mo, W, Ag, Al, Cu, Ni, Ti, Cr, Au

**Mask and Maskless Aligners:** Blank Photomasks (for mask making) 4”x4” (Cr), 5”x5” (Cr), 3”x3” (Fe$_2$O$_3$), 4”x4” (Fe$_2$O$_3$), 5”x5” (Fe$_2$O$_3$)

**Contact Angle Measurement:** syringes and needles for liquids other than water.

**Filmetrics:** Si wafer for background measurement

**Electrical Test Probe Station:** Spare contact probes.

**Gases**
Silane, Ammonia, Hydrogen, Dichlorosilane, Forming Gas (4%H$_2$, Balance N$_2$), UHP nitrogen, Oxygen, N$_2$O, CF$_4$, C$_4$F$_8$, CHF$_3$, Helium, SF$_6$, Argon, Liquid CO$_2$